

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**  
 Created on: **05/31/2022**

Details for "LM26735-12"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
LM26735-12	SNPB	Level-3-235C-168 HR	Texas Instruments Electronics	KTW   7	10.1 x 8.9 x 4.5	1740.3

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
No	Affected	Yes	Affected

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Aluminum and Its Alloys	Aluminum	7429-90-5	0.000001	0.000151	2	0	0
Copper and Its Alloys	Copper	7440-50-8	0.663085	99.997285	999973	0.038102	381
Copper and Its Alloys	Iron	7439-89-6	0.000003	0.000452	5	0	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000002	0.000302	3	0	0
Precious Metals	Silver	7440-22-4	0.000012	0.00181	18	0.000001	0
Sub-Total			<b>0.663103</b>	<b>100</b>	<b>1000000</b>	<b>0.038103</b>	<b>381</b>
<b>Die Attach Adhesive</b>							
Other Nonferrous Metals and Alloys	Lead	7439-92-1	5.817135	95.499997	955000	0.334264	3343
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.121825	2.000003	20000	0.007	70
Precious Metals	Silver	7440-22-4	0.152281	2.5	25000	0.00875	88
Sub-Total			<b>6.091241</b>	<b>100</b>	<b>1000000</b>	<b>0.350014</b>	<b>3500</b>
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	945.993104	99.68	996800	54.358565	543586
Copper and Its Alloys	Phosphorus	7723-14-0	0.094903	0.01	100	0.005453	55
Other Nonferrous Metals and Alloys	Tin	7440-31-5	1.423545	0.15	1500	0.0818	818
Precious Metals	Silver	7440-22-4	1.518448	0.16	1600	0.087253	873
Sub-Total			<b>949.03</b>	<b>100</b>	<b>1000000</b>	<b>54.533071</b>	<b>545331</b>
<b>Lead Frame Plating</b>							
Other Nonferrous Metals and Alloys	Lead	7439-92-1	2.466	15	150000	0.141701	1417
Other Nonferrous Metals and Alloys	Tin	7440-31-5	13.974	85	850000	0.802973	8030
Sub-Total			<b>16.44</b>	<b>100</b>	<b>1000000</b>	<b>0.944674</b>	<b>9447</b>
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	676.107783	89	890000	38.85044	388504
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	22.79015	3	30000	1.309565	13096
Thermoplastics	Epoxy	85954-11-6	60.773733	8	80000	3.492174	34922
Sub-Total			<b>759.671666</b>	<b>100</b>	<b>1000000</b>	<b>43.65218</b>	<b>436522</b>
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	8.387435	100	1000000	0.481958	4820
Sub-Total			<b>8.387435</b>	<b>100</b>	<b>1000000</b>	<b>0.481958</b>	<b>4820</b>
<b>Total</b>			<b>1740.283445</b>			<b>100</b>	<b>1000000</b>

**Important Note**  
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.  
[See Glossary of Terms for more details.](#)

**Important Part Information**  
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSLs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**  
[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**

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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.